Build Up HDI (Standard)

HDI12_2+8(10b)+2_1,35_35_engl

12 - Layers

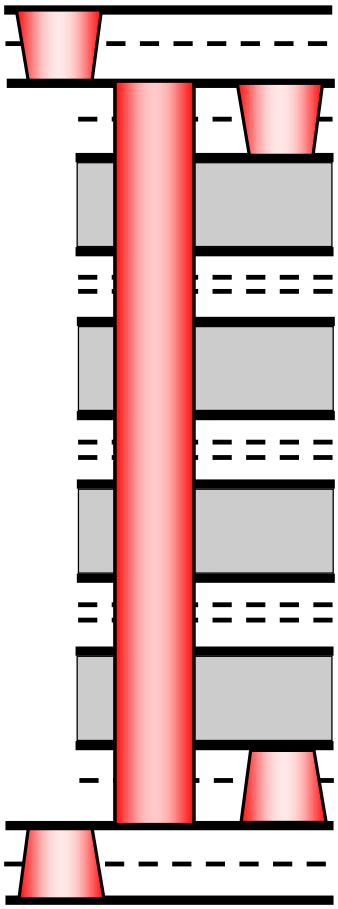
Core: 0,10 mm Cu 35/35 µm

WE-Articel No.:

2 + 8(10B) + 2

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	9 µm		30	
					1 x 1080	60	
	3			35 µm		33	
			0,100 mm			100	
	4			35 µm		33	
					2 x 1080	124	
	5			35 µm		33	
			0,100 mm			100	
	6			35 µm		33	
					2 x 1080	124	
	7			35 µm		33	
			0,100 mm			100	
	8			35 µm		33	
					2 x 1080	124	
	9			35 µm		33	
			0,100 mm			100	
	10			35 µm		33	
					1 x 1080	60	
	11		Foil	9 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1360

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,35**	+/-	0,11	mm				
thickness with electro plated Cu:	1,44	+/-	0,14	mm				
total thickness with soldermask	1,50	+/-	0,16	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
29.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00	14+